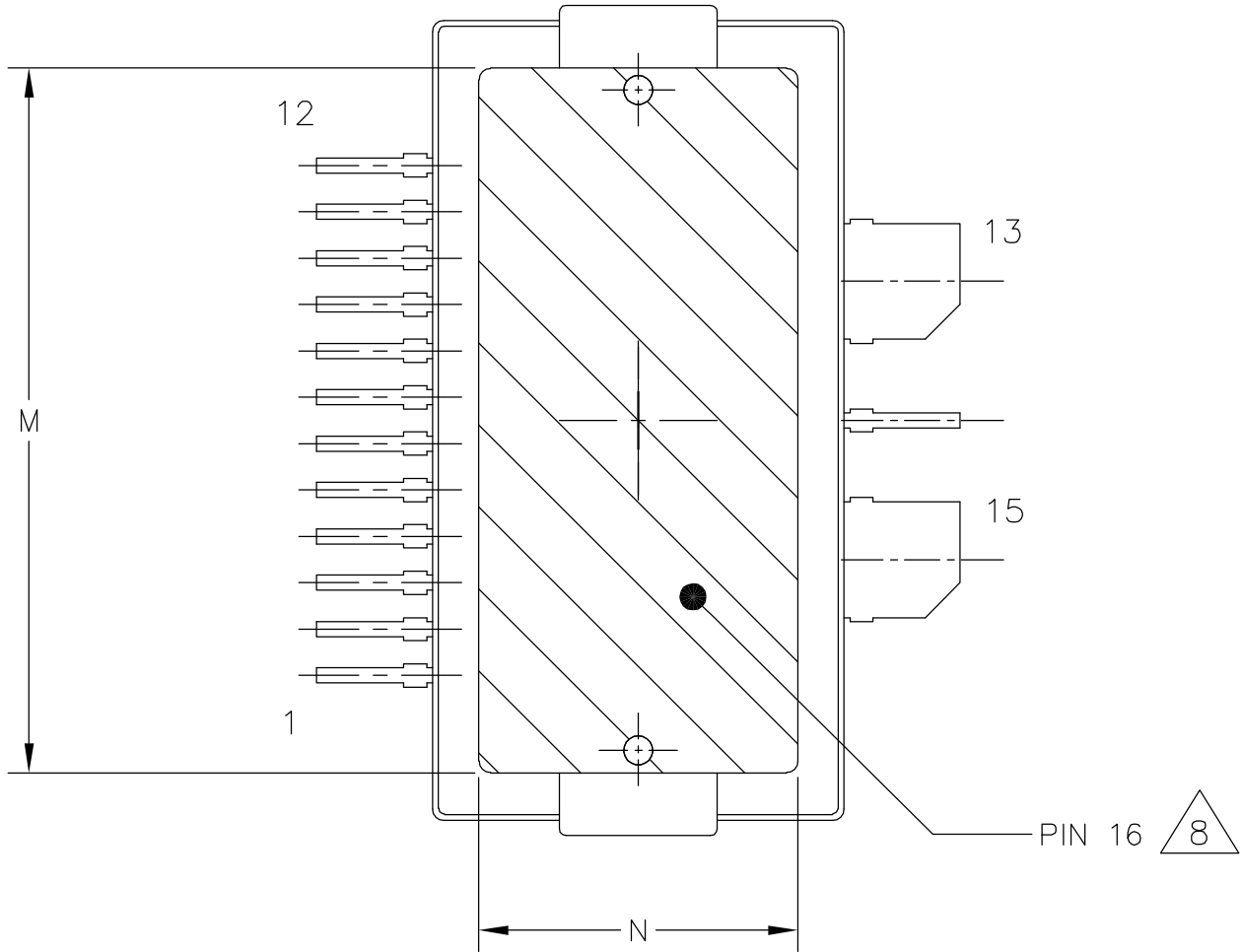


|  |                           |                            |
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| TITLE:<br><br>TO-270WB-15                        | DOCUMENT NO: 98ASA00630D  | REV: A                     |
|  | STANDARD: NON-JEDEC       |                            |
|  | SOT1722-1                 | 21 JAN 2016                |



VIEW Y-Y

|  |                           |                            |        |
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|  | SOT1722-1                 | 21 JAN 2016                |        |



NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE H IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM) PER SIDE. DIMENSIONS D AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS bb AND b1 DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 INCH (0.13 MM) TOTAL IN EXCESS OF THE bb AND b1 DIMENSIONS AT MAXIMUM MATERIAL CONDITION.
6. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.
7. DIMENSION A2 APPLIES WITHIN ZONE J ONLY.
8. HATCHING REPRESENTS THE EXPOSED AND SOLDERABLE AREA OF THE HEAT SLUG. DIMENSIONS M AND N REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF EXPOSED AREA OF THE HEAT SLUG.
9. THESE SURFACES OF THE HEAT SLUG ARE NOT PART OF THE SOLDERABLE SURFACES AND MAY REMAIN UNPLATED.

| DIM | INCH     |      | MILLIMETER |       | DIM | INCH           |      | MILLIMETER     |      |
|-----|----------|------|------------|-------|-----|----------------|------|----------------|------|
|     | MIN      | MAX  | MIN        | MAX   |     | MIN            | MAX  | MIN            | MAX  |
| AA  | .099     | .105 | 2.51       | 2.67  | M   | .600           | ---- | 15.24          | ---- |
| A1  | .039     | .043 | 0.99       | 1.09  | N   | .270           | ---- | 6.86           | ---- |
| A2  | .040     | .042 | 1.02       | 1.07  | bb  | .097           | .103 | 2.46           | 2.62 |
| D   | .688     | .692 | 17.48      | 17.58 | b1  | .010           | .016 | 0.25           | 0.41 |
| D1  | .712     | .720 | 18.08      | 18.29 | c1  | .007           | .011 | 0.18           | 0.28 |
| E   | .551     | .559 | 14.00      | 14.20 | e   | .020 BSC       |      | 0.51 BSC       |      |
| E1  | .353     | .357 | 8.97       | 9.07  | e1  | .040 BSC       |      | 1.02 BSC       |      |
| E2  | .346     | .350 | 8.79       | 8.89  | e2  | .253 INFO ONLY |      | 6.43 INFO ONLY |      |
| E3  | .132     | .140 | 3.35       | 3.56  | e3  | .120 BSC       |      | 3.05 BSC       |      |
| F   | .025 BSC |      | 0.64 BSC   |       | aaa | .004           |      | 0.10           |      |
|     |          |      |            |       | bbb | .008           |      | 0.20           |      |

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